PATENT ASSIGNMENT

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SUBMISSION TYPE:		NEW ASSIGNMENT		
NATURE OF CONVEYANCE:		ASSIGNMENT		
CONVEYING PARTY DATA				
		N	lame	Execution Date
Ming-Chung LIANG				07/19/2010
Chii-Ping CHEN				07/19/2010
RECEIVING PARTY DATA				
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.			
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park			
City:	Hsinchu			
State/Country:				
Postal Code:	300			
PROPERTY NUMBERS Total: 1				
Property Type			Number	
		128/1	12841321	
Application Number: 12841321 CORRESPONDENCE DATA XXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXXX				
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ATTORNEY DOCKET NUMBER:			T5057-Y149U	
NAME OF SUBMITTER:			Yoon S. Ham	
Total Attachments: 1 source=efiledassgn#page1.tif				

9-0693 Docket No. T5057-Y149U

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Ming-Chung LIANG
- Chii-Ping CHEN 2)

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

INTEGRATED CIRCUITS AND METHODS FOR FORMING THE INTEGRATED CIRCUITS

for which an application for United States Letters Patent was filed on 7-22-10, and identified by United (a) States Patent Application No. 12/841, 321 ; or

(b) for which an application for United States Letters Patent was executed on

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) _____ Ming-chung Liang_____ Name: Ming-Chung LIANG

2) Chii-Ping Chen Name: Chii-Ping CHEN

اهد / ۳/ ۱۹ Date:

7,19,>010 Date:

RECORDED: 07/22/2010